

ABSTRACT OF THE DISCLOSURE

A process for producing a multilayer printed circuit board produced characterized by using a special thermosetting epoxy resin composition comprising (a) an epoxy resin, (b) a crosslinking agent and (c) a polyfunctional epoxy resin, for forming a thermosetting copper-clad adhesive resin sheet, which cover an interlayer circuit plate, followed by etching of cured adhesive resin for forming holes for interstitial via holes (IVH) having a small diameter using a special etching solution comprising (A) an amine as a solvent, (B) an alkali metal compound, and (C) an alcohol as a solvent, is suitable for mass production of multilayer printed circuit boards having IVH excellent in connection reliability and electrical properties.

Fig. 1

This Sheet Has Been Replaced

